

PRODUCT NUMBER

95609-XXXLF

PLATING

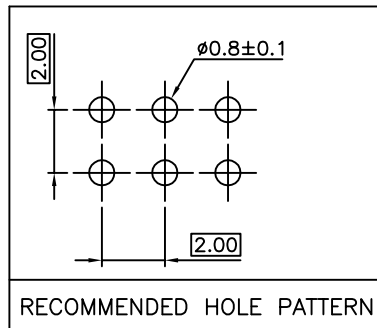
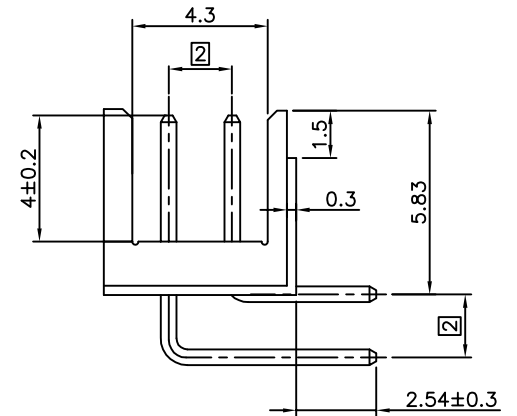
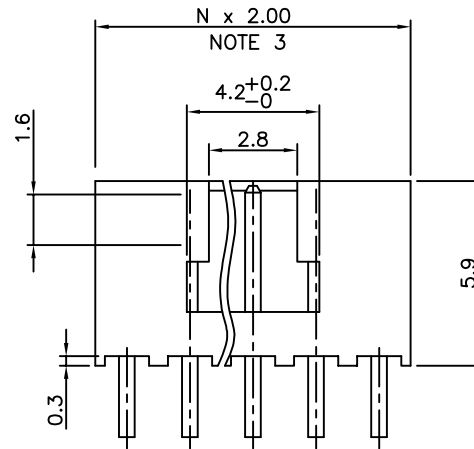
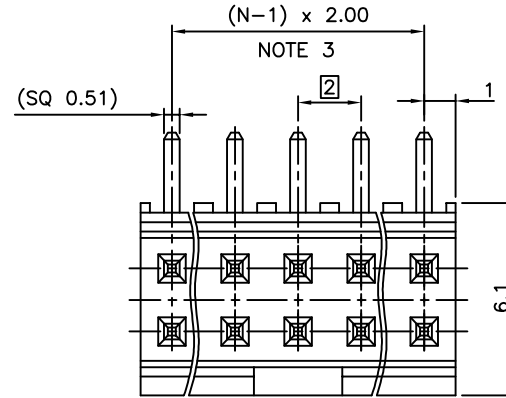
- 0 = 0.20µm Au/GXT
- 1 = 0.76µm Au/GXT
- 3 = 0.38µm Au/GXT
- 5 = 0.38µm GXT
- 6 = 0.76µm GXT

RoHS COMPATIBLE, SEE NOTE 6
TOTAL NB OF POSITIONS, 08 TO 34

1.27µm Ni MIN UNDERPLATING

NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR CREAM
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.
5. STANDARD PACKAGING IN POLYBAGS.
6. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - b - LABELLING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - c - THIS PRODUCT MEETS EUROPEAN DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
SEE NOTES		ISO 1302		ISO 406 ISO		101		MINITEK HEADER	
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm		title	
C	F05-0128	LMU	05.02.21	angles	.X ±0.3	mm		SHR HEADER	
D	F06-0210	LMU	06.07.04	linear	.XX ±0.13	scale 7:1		2.00mm TMT R/A	
E	F08-0145	ELA	15.04.08	±2'	.XXX ±0.05			dwg no	
F	B-19190	LMU	14.10.24	dr	L.MULIN	02.06.19		sheet 1 of 1 size	
G	F-21746	AMA	15.08.21	engr	J.COMPAGNON	02.06.19		95609 A3	
				chr				type	
				appd	JMC	02.06.19		CUSTOMER Drawing	
sheet index	revision sheet								